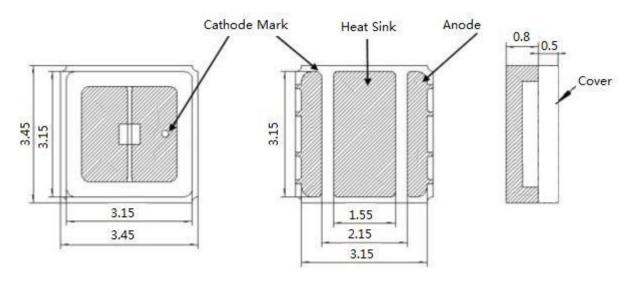
## Specification for Approval

#### ♦ Features

- \* Emitting view angle 120°
- \* Suitable for all SMT assembly method.
- \* IR reflow soldering and vapor phase reflow soldering.
- \* For disinfection

## Package Dimensions



(Unit: mm)

#### Notes:

- 1. All dimensions are in mm.
- 2. Tolerance is ±0.25mm unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.

## Specification for Approval

### Description

Model No.	Material		Emitted		Lens Color			
3535UV - 280	GaN	I UV		Wa		ter		
♦ Absolute Maximum Ratings (T <sub>A</sub> =25°)								
Parameter		Symbol		Rating		Unit		
Power Dissipation		PD		250		mW		
Forward Current (DC)		l <sub>F</sub>		40		mA		
Peak Forward Current •		I <sub>FP</sub>		100		mA		
Reverse Voltage		V <sub>R</sub>		5.0		V		
Operation Temperature Range		T <sub>op</sub> -		-2	5to+85	°C		
Storage Temperature Range		T <sub>stg</sub>		-40to+100		°C		
Soldering Temperature 260°05sec			5sec					

\* Pulse width≤0.1msec Duty Ratio ≤1/10

# ◆ Electrical and Optical Characteristics (T<sub>A</sub>=25°)

Parameter	Test Condition	Symbol	Min	Тур	Max	Unit
Forward Voltage( v <sub>F</sub> )	I <sub>F</sub> =40mA	$V_{\rm F}$	5.0	6.2	7.0	V
View Angle	I <sub>F</sub> =40mA	201/2		120		deg
Reverse Current	$V_R$ =-5V	I <sub>R</sub>			2	μA
Peak Wavelength	I <sub>F</sub> =40mA	Wp	275	280	283	nm
Dedient newer	I <sub>F</sub> =40mA	Ee	3.0		3.5	Mw
Radiant power			3.5		4.0	Mw

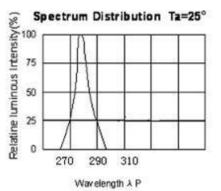
Notes:

1. The dominant Wavelength,  $\lambda_{dom}$  is derived from the CIE chromaticity diagram and represents the single wavelength which define the color of the device.

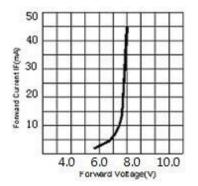
2. 201/2 is the off-axis angle where the luminous intensity is one half the on-axis intensity.

3. Luninous intensity is measured by \*\*\* equipment on Top LED in the same lot.

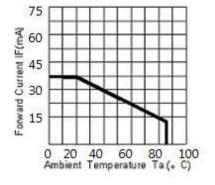
# Typical Electrical/Optical Characteristic Curves (If=40mA; $T_A$ =25° %



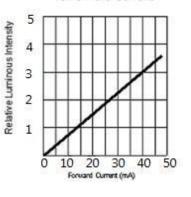
Forward Current vs.Forward Voltage



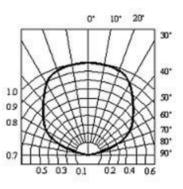




Relative Luminous Intensity vs Forward Current



**Radiation Diagram** 



## Specification for Approval

## Reliability performance

### Testitems and result

Test	Test item	Test conditions	Test duration	Sample size	AC/RE
classification					
Life test	Room temperature	Ta=25±5°C			
	DC operating life test	IF=40mA	100hrs	30pcs	0/1
	Thermal shock Test	-10±5°C←→+100±5°C 5min 10sec 5min	50cysles	30pcs	0/1
	Temperature cycle test	-40±5°C←→+85±5°C 30min 5sec 30min	50cysles	30pcs	0/1
Environment test	High temperature & High humidity test	Ta=85±5°C RH=85%±0.5%RH	100hrs	30pcs	0/1
	High temperature storage	Ta =100±5 °C	100hrs	30pcs	0/1
	Low temperature storage	Ta =-55±5°C	100hrs	30pcs	0/1
Mechanical test	Resistance to soldering heat	Ta =230±5°C	5sec	30pcs	0/1
	Lead integrity	Load 2.5N(0.25KGf) 0 °C ~90 °C ~ 0°C	3times	30pcs	0/1